EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	44	("20020132062" | "20020179126" | "20020197002" | "20030002019" | "20030016337" | "20030038327" | "20030054588" | "20030102552" | "20030146464" | "20030155643" | "20030161949" | "20030178635" | "20030183916" | "20040266038" | "4849071" | "4945769" | "5445991" | "5470797" | "5616514" | "5683591" | "5804083" | "5922212" | "5963788" | "6318175" | "6423563" | "6477901" | "6492309" | "6500348" | "6521508" | "6528875" | "6590267" | "6602351" | "6621392" | "6625047" | "6625342" | "6716275" | "6739497" | "6764875" | "6815361" | "6818464" | "6822326" | "6835657" | "6847124" | "6858910").PN. OR ("7221033").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/23 00:55
L8	1	"20060049471"	US-PGPUB; USPAT	OR	OFF	2008/06/23 01:00
L9	59	257/E21.32	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 01:01

L10	1608	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 01:02
L11	5709	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 01:08
L12	2068	257/701	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 01:10
L13	753	257/710	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 01:19
L14	5130	257/723	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 01:36
L15	2003	257/704	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 01:38
L16	1510	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 01:49
L17	1034	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 02:05

L18	6110	438/106	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 02:07
L19	1199	438/121	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 02:09
L20	2117	438/125	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 02:19
L21	566	438/456	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 02:28
L22	2133	438/723	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 02:43
L23	2550	216/2	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 02:51
L24	1045	216/79	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 03:04
L25	1145	73/504.12	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 03:16

L26	727	73/504.02	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 03:26
L27	0	(semiconductor or die) and flexible near tape with power near layer and ground near layer	USPAT	OR	OFF	2008/06/23 03:29
L28	0	(semiconductor or die) and flexible near tape same power near layer and ground near layer	USPAT	OR	OFF	2008/06/23 03:29
L29	1	(semiconductor or die or chip or dice or IC) and flexible near tape same power near layer and ground near layer	USPAT	OR	ON	2008/06/23 03:29
L30	0	(semiconductor or die or chip or dice or IC) and flexible near tape and tape with power near layer and ground near layer	USPAT	OR	ON	2008/06/23 03:31
L31	13	(semiconductor or die or chip or dice or IC) and flexible near (tape or substrate) and (tape or substrate) with power near layer and ground near layer	USPAT	OR	ON	2008/06/23 03:31
L32	61	(semiconductor or die or chip or dice or IC) and flexible near (tape) and (tape) with power and ground	USPAT	OR	ON	2008/06/23 03:34
L33	537	73/504.14	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/23 03:36
S1	71	micro near electronic with structure	USPAT	OR	OFF	2007/11/24 22:08
S2	11949	MEMS	USPAT	OR	OFF	2007/11/25 21:34
S3	147	MEMS with cap	USPAT	OR	OFF	2007/11/24 22:32

S4	361	MEMS with cover$3	USPAT	OR	OFF	2007/11/24 23:12
S5	319	S4 not S3	USPAT	OR	OFF	2007/11/24 22:32
S6	80	MEMS with lid	USPAT	OR	OFF	2007/11/24 23:13
S7	49	("0557132" | "3244947" | "3259814" | "3274458" | "3316465" | "3489965" | "3916080" | "3959577" | "3993123" | "4168480" | "4257905" | "4449580" | "4511873" | "4563697" | "4565901" | "4897508" | "5046161" | "5325265" | "5475280" | "5627396"). PN. OR ("6025767"). URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/11/25 20:06
S8	934	MEMS same (insulat$3 or dielectric) with (layer or film)	USPAT	OR	OFF	2007/11/25 20:19
S9	303	MEMS with cap$4 and (insulat$3 or dielectric) with (layer or film)	USPAT	OR	OFF	2007/11/25 20:20
S10	44	("20020132062" | "20020179126" | "20020197002" | "20030002019" | "20030016337" | "20030038327" | "20030054588" | "20030102552" | "20030146464" | "20030155643" | "20030161949" | "20030178635" | "20030183916" | "20040266038" | "4849071" | "4945769" | "5445991" | "5470797" | "5616514" | "5683591" | "5804083" | "5922212" | "5963788" | "6318175" | "6423563" | "6477901" | "6492309" | "6500348" | "6521508" | "6528875" | "6590267" | "6602351" |	US-PGPUB; USPAT; USOCR	OR	OFF	2007/11/25 20:39

		"6621392" | "6625047" | "6625342" | "6716275" | "6739497" | "6764875" | "6815361" | "6818464" | "6822326" | "6835657" | "6847124" | "6858910").PN. OR ("7221033").URPN.				
S11	6	("20020071169" | "20020096421" | "20020179986" | "20030116845" | "20030151479").PN. OR ("7138293").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/11/25 20:35
S12	1	"6465280".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2007/11/25 20:39
S13	2238	MEMS and (cap$4 or lid or cover$3) with (open $3 or gap or spac$3)	USPAT	OR	OFF	2007/11/25 21:35
S14	87	MEMS and (cap$4 or lid or cover$3) with (open $3 or gap or spac$3) same pad	USPAT	OR	OFF	2007/11/25 21:43
S15	593	MEMS and (cap$4 or lid or cover$3) with (open $3 or gap or spac$3) and pad	USPAT	OR	OFF	2007/11/25 21:43
S16	506	S15 not S14	USPAT	OR	OFF	2007/11/25 22:07
S17	1	"6452238".pn.	USPAT	OR	OFF	2007/11/25 22:42
S18	40	257/E21.32	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/11/25 22:43
S19	5311	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/11/25 23:30
S20	1978	257/701	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/11/26 00:21

S21	5712	438/106	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/11/26 00:58
S22	984	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/11/26 00:59
S23	25	MEMS same cap with (dielectric or insulat$3)	USPAT	OR	ON	2007/11/26 01:03
S24	147	MEMS and cap with (dielectric or insulat$3)	USPAT	OR	ON	2007/11/26 01:03

6/23/08 3:46:06 AM
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